

CLAIMS

1. A dicing/die bonding sheet adhesively bonded to a semiconductor wafer prior to the dicing of said semiconductor wafer, wherein said dicing/die bonding sheet is provided with a base film, an undercoat layer formed on the above-mentioned base film, and a silicone based adhesive agent layer formed on the above-mentioned undercoat layer and having an adhesive surface adhesively bonded to the above-mentioned semiconductor wafer.
5
2. The dicing/die bonding sheet according to claim 1, wherein the above-mentioned silicone based adhesive agent layer can be stripped from the above-mentioned undercoat layer after bonding to the above-mentioned semiconductor wafer.
- 10 3. The dicing/die bonding sheet according to claims 1 or 2, wherein the above-mentioned undercoat layer is a laminate made up of at least two layers.
4. The dicing/die bonding sheet according to any of claims 1 through 3, wherein the above-mentioned base film has a surface area that is not less than the above-mentioned semiconductor wafer.
- 15 5. The dicing/die bonding sheet according to any of claims 1 through 4, which is coated with a strippable protective layer.
6. A method of preparing the dicing/die bonding sheet according to claim 1, which includes the step of forming an undercoat layer and a silicone based adhesive agent layer on a base film.
- 20 7. The method of preparing a dicing/die bonding sheet according to claim 1, which includes the step of forming a silicone based adhesive agent layer and an undercoat layer on a stripping layer, the step of applying a base film to the surface of the above-mentioned undercoat layer, and the step of peeling off the above-mentioned stripping layer.
8. The method of preparing a dicing/die bonding sheet according to claim 7, which
25 further includes the step of forming a strippable protective layer on the above-mentioned silicone based adhesive agent layer after the step of peeling off the above-mentioned stripping layer.

9. The method of preparing a dicing/die bonding sheet according to claim 5, which includes the step of forming a silicone based adhesive agent layer and an undercoat layer on a strippable protective layer and the step of applying a base film to the surface of the above-mentioned undercoat layer.